

Specification of Thermoelectric Module

TEFC1-07441D13

Description

The 74 couples, 18.25 mm × 13.90 mm size ingle module which is made of selected high performance ingot to achieve superior cooling performance and greater delta T up to 70 °C , designed for superior cooling and heating up to 100 °C /200 °C applications. If higher operation or processing temperature is required, please specify, we can design and manufacture the custom made module according to your special requirements.

Features

- No moving parts, no noise, and solid-state
- Compact structure, small in size, light in weight
- Environmental friendly
- RoHS compliant
- Precise temperature control
- Exceptionally reliable in quality, high performance

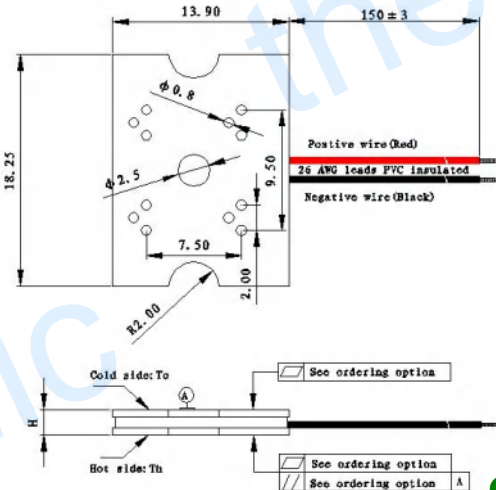
Application

- Food and beverage service refrigerator
- Portable cooler box for cars
- Liquid cooling
- Temperature stabilizer
- CPU cooler and scientific instrument
- Photonic and medical systems

Performance Specification Sheet

Th (°C)	27	50	Hot side temperature at environment: dry air, N ₂
DT _{max} (°C)	70	79	Temperature Difference between cold and hot side of the module when cooling capacity is zero at cold side
U _{max} (Voltage)	9.17	9.90	Voltage applied to the module at DT _{max}
I _{max} (amps)	4.1	4.1	DC current through the modules at DT _{max}
Q _{Cmax} (Watts)	24.3	26.2	Cooling capacity at cold side of the module under DT=0 °C
AC resistance (ohms)	1.70	1.83	The module resistance is tested under AC
Tolerance (%)	10%		For thermal and electricity parameters

Geometric Characteristics Dimensions in millimeters



Manufacturing Options

- | | |
|---|-------------------------------------|
| A. Solder: | B. Sealant: |
| 1. T100: BiSn (Tmelt=138°C) | 1. NS: No sealing (Standard) |
| 2. T200: CuAgSn (Tmelt = 217°C) | 2. SS: Silicone sealant |
| 3. T240: SbSn (Tmelt = 240°C) | 3. EPS: Epoxy sealant |
| C. Ceramics: | D. Ceramics Surface Options: |
| 1. Alumina (Al ₂ O ₃ , white 96%) | 1. Blank ceramics (not metalized) |
| 2. Aluminum Nitride (AlN) | 2. Metalized |

Ordering Option

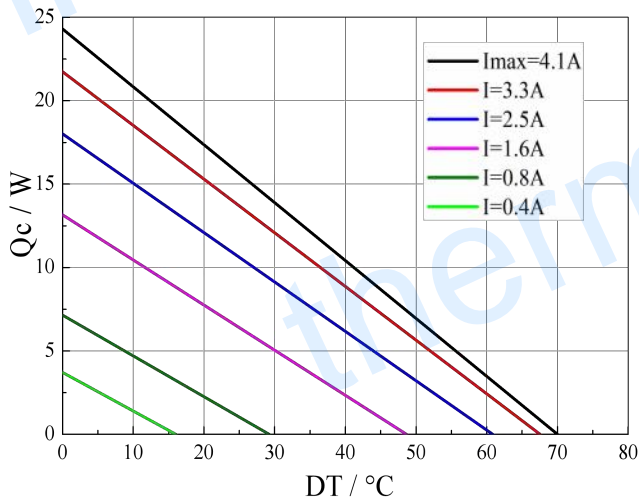
Suffix	Thickness H (mm)	Flatness/ Parallelism (mm)	Lead wire length(mm) Standard/Optional length
TF	0: 2.1±0.10	0: 0.05/0.05	150±3/Specify
TF	1: 2.1±0.03	1: 0.02/0.02	150±3/Specify

Eg. TF01: Thickness 2.1± 0.10 (mm) and Flatness 0.02 / 0.02(mm)

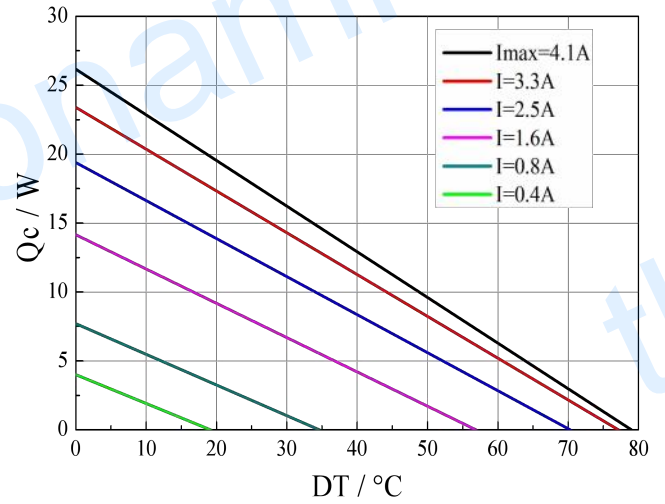
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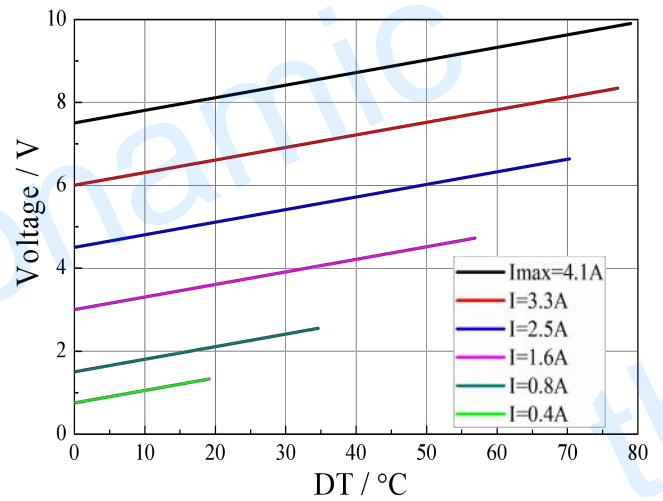
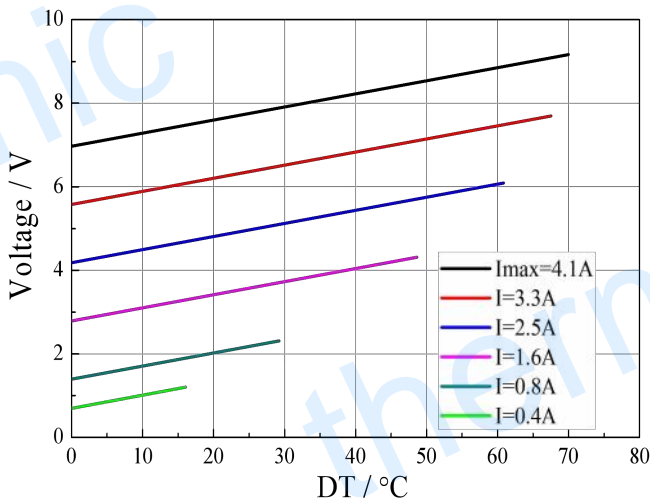
Performance Curves at $T_h=27^\circ\text{C}$



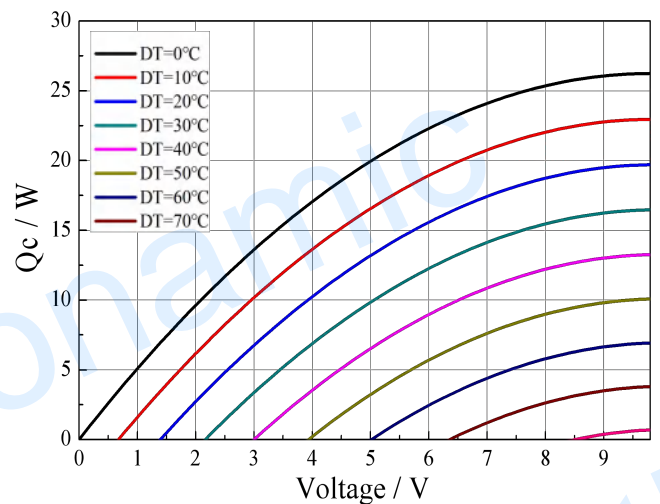
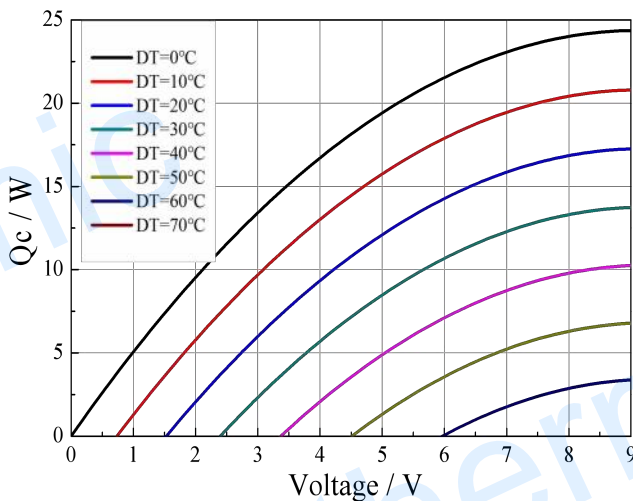
Performance Curves at $T_h=50^\circ\text{C}$



Standard Performance Graph $Q_c = f(DT)$



Standard Performance Graph $V = f(DT)$

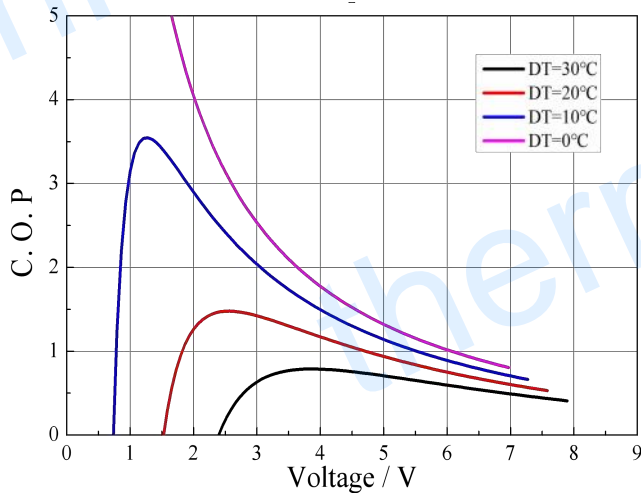


Standard Performance Graph $Q_c = f(V)$

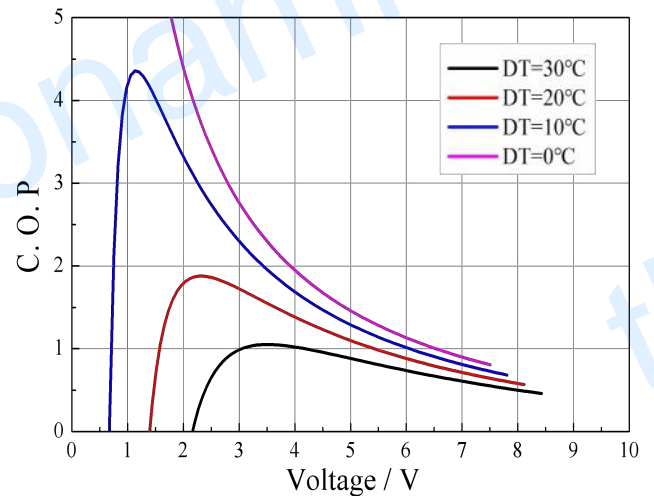
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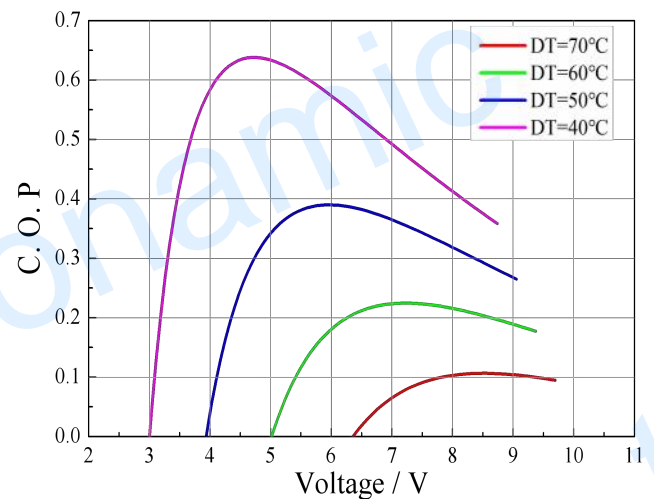
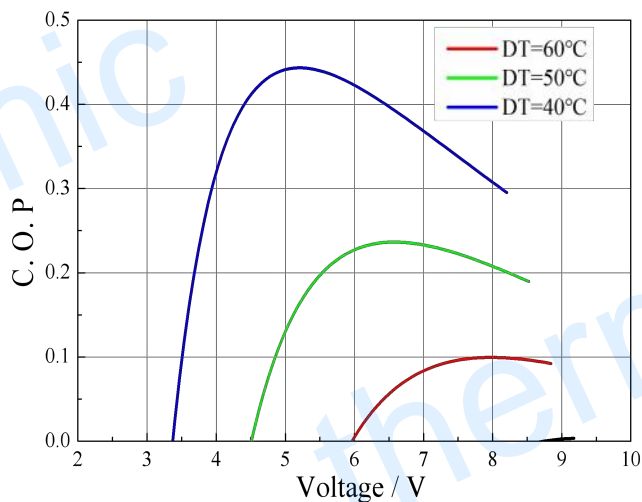
Performance Curves at $T_h=27\text{ }^\circ\text{C}$



Performance Curves at $T_h=50\text{ }^\circ\text{C}$



Standard Performance Graph $COP = f(V)$ of DT ranged from 0 to 30 $^\circ\text{C}$



Standard Performance Graph $COP = f(V)$ of DT ranged from 40 to 60/70 $^\circ\text{C}$

Remark: The coefficient of performance (COP) is the cooling power Q_c /Input power ($V \times I$).

Operation Cautions

- Cold side of the module stucked on the object being cooled
- Hot side of the module mounted on a heat radiator
- Operation below I_{max} or V_{max}
- Work under DC

Note: All specifications subject to change without notice.